AMENDMENTS TO THE CLAIMS

Please cancel claims 1-15 without disclaimer or prejudice.

Please add claims 16-22.

16. (New) A land grid array on a carrier, comprising:

(a) a plurality of electrical interconnections arranged into a plurality of arrays;

(b) a electrically conductive exterior sash surrounding the exterior perimeter of the plurality of arrays, the exterior sash having a width defined by an inner edge closest to the array and an outer edge, the width of the exterior sash larger than a frame having a connector to be positioned onto the array, the exterior sash having a height substantially the same height as the plurality of electrical interconnections extending above the plane of the carrier;

(c) at least one interior sash surrounding a interior length of each of a plurality of arrays of electrical interconnections facing another of the plurality of arrays of electrical interconnections, the enclosed arrays being specific to one of a plurality of individual chip domains residing on the multichip module;

(d) a plurality of electrical connections between the exterior and/or interior sash and array at selected electrical interconnections;

(e) wherein the exterior and/or interior sash is a voltage path for any of a plurality of other components on the carrier.

17. (New) A land grid array, as in claim 16, wherein the interior and/or exterior sash further comprises a noble or semi-noble surface finish plating.

18. (New) A land grid array, as in claim 17, wherein the noble or semi-noble surface finish plating is made from a pure metal or an alloy from the group consisting of: nickel, gold, palladium.

19. (New) A land grid array, as in claim 16, wherein the exterior and/or interior sash is of the same material as the plurality of electrical interconnections.

20. (New) A land grid array, as in claim 16, wherein the exterior and/or interior sash is electrically connected to a logic ground voltage.

21. (New) A land grid array, as in claim 16, wherein the exterior and/or interior sash is manufactured simultaneously with the manufacture of the plurality of electrical interconnections.

22. (New) A carrier with a land grid array for use with a land grid array interposer connector, the land grid array comprising:

(a) a multitude of electrical interconnections arranged into plurality of arrays;

(b) an electrically conductive exterior sash surrounding the outer periphery of the plurality of arrays, the exterior sash having a width defined by an inner edge closest to the plurality of arrays and an outer edge, said exterior conductive sash comprising:

(i) placement means for the land grid array interposer to rest upon when placed on top of the land grid array for electrical connection;

(ii) means to provide a more uniform height and surface finish of the electrical interconnections spanning interior regions of an area toward the outer periphery of the array where the interposer is placed upon the placement means;

(iii) means to prevent particulate and gaseous contamination of the array of electrical interconnections when an interposer is placed onto the array;

(iv) means to provide a voltage path for any of a plurality of other components electrically connected to the carrier; and

(c) at least one interior sash proximal to an inner edge of each of a plurality of arrays of electrical interconnections, the inner edge defined as the edge facing another of the plurality of arrays of electrical interconnections, the enclosed arrays being specific to one of a plurality of individual chip domains residing on a multichip module.